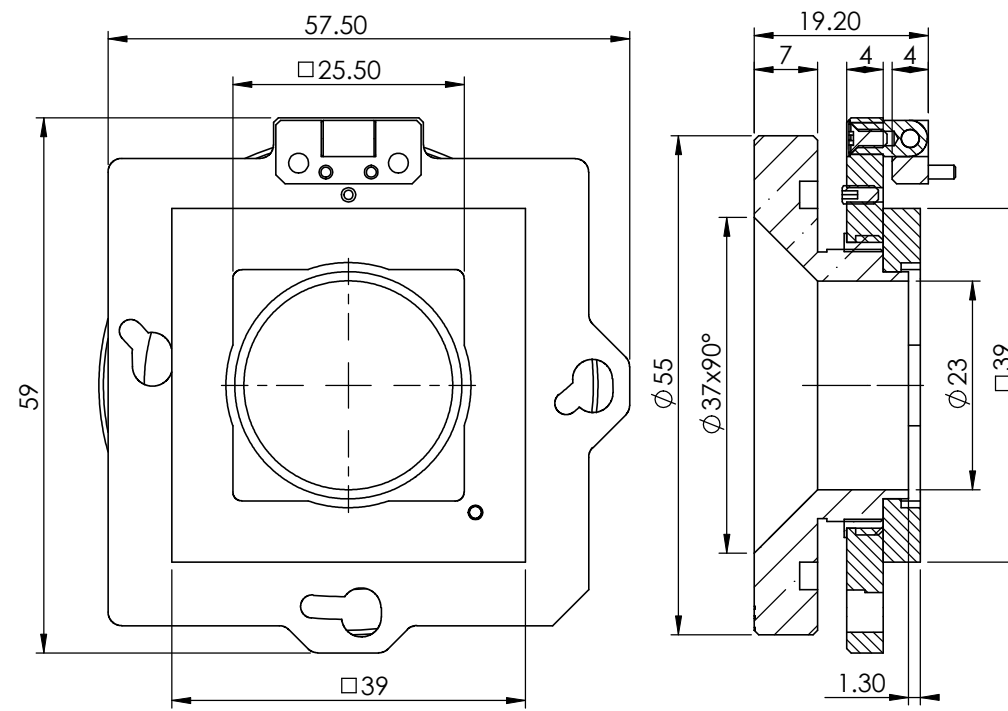
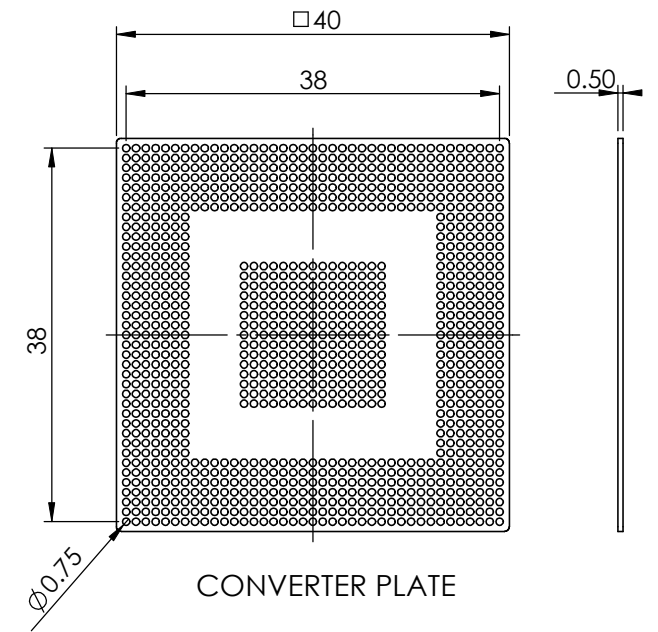


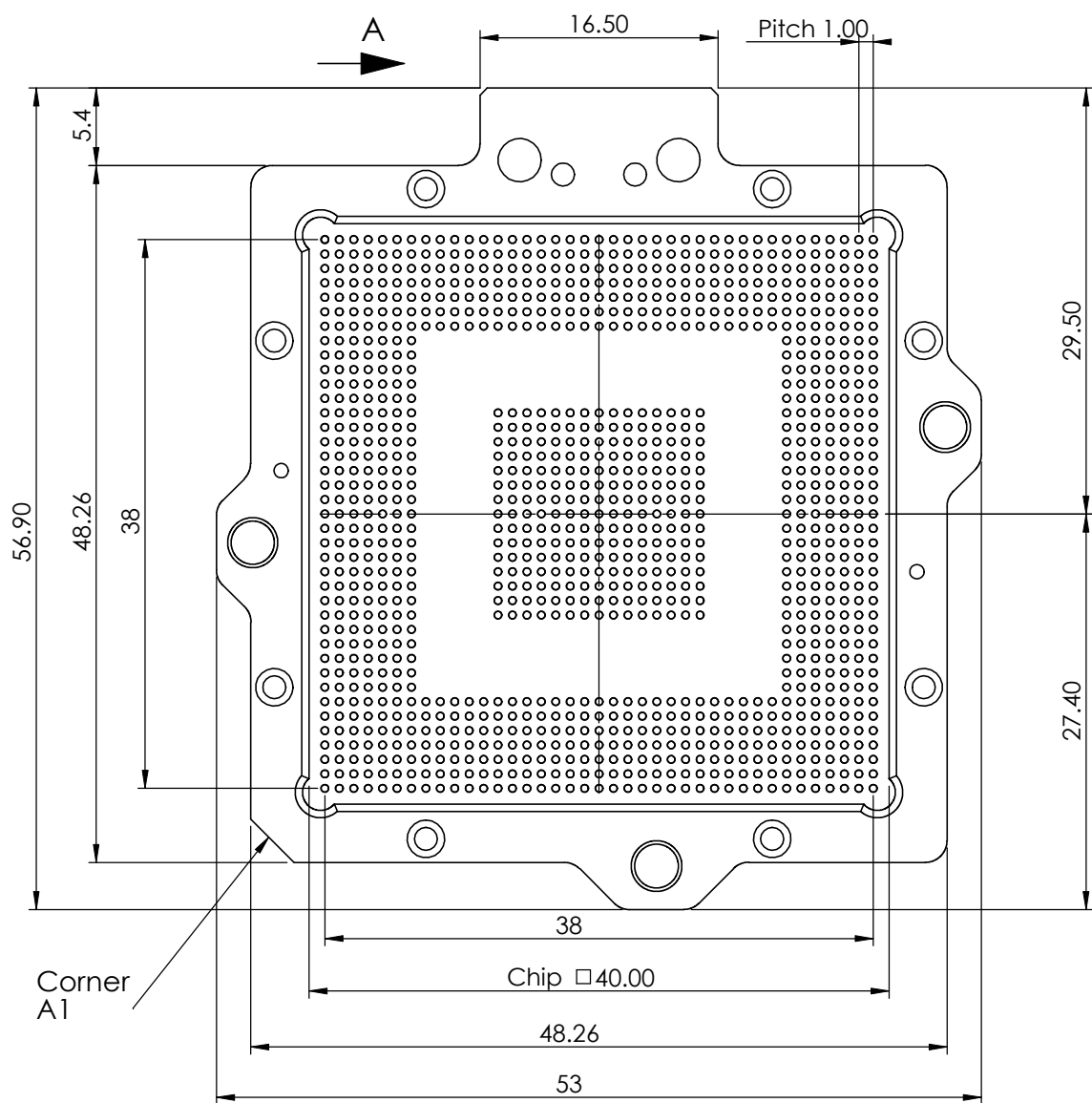
VUE A



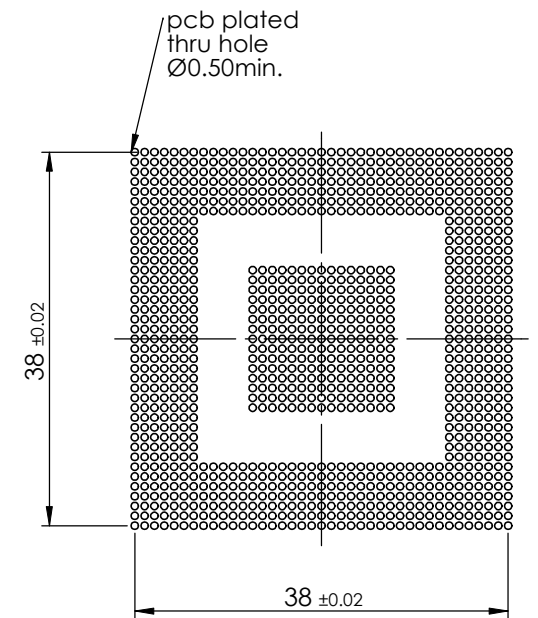
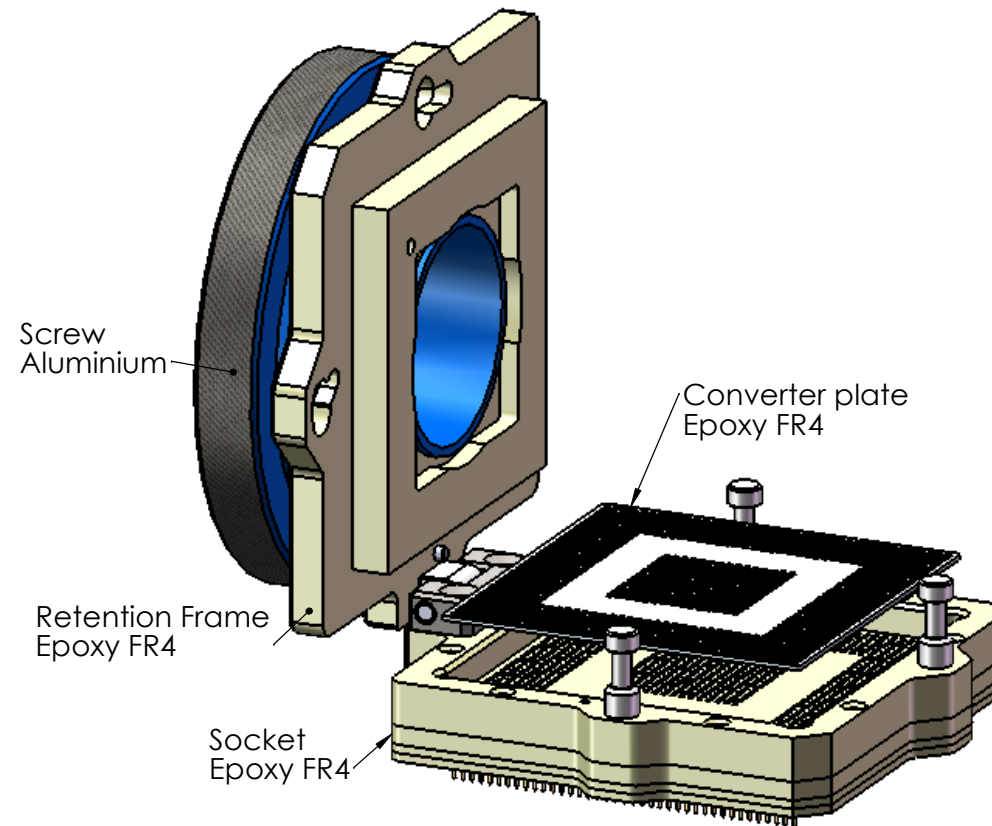
RETENTION FRAME



CONVERTER PLATE



Corner A1



PCB LAYOUT

Socket designed for chip
LGA 1.3 to 3.8 thickness without die
BGA 1.3 to 3.3 thickness with balls and without die

UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN MILLIMETERS SURFACE FINISH: GENERAL TOLERANCES ISO 2768m		Remark: BGA/LGA Economic Clamshell socket, 1121 pins, Pitch 1.00mm, matrix 39x39 Retention frame code AB= Opening 25.5x25.5 on Low profile				 www.e-tec.com	
Patented		Visa	Date	Drawn by	Date	Visa	Designed and manufactured by www.happ.ch
DRAWN		sme	02.09.2010	sme	02.09.2010		"E-tec order code"
CHK'D							LPE1121-1070-39AB95C A3H
APPV'D		sme	02.09.2010				"Production code"
				Echelle: 2:1		LPE1121-10-09415-39ABA-C 0	
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						SHEET 1 OF 1	